

MURS360B ULTRAFAST PLASTIC RECTIFIER

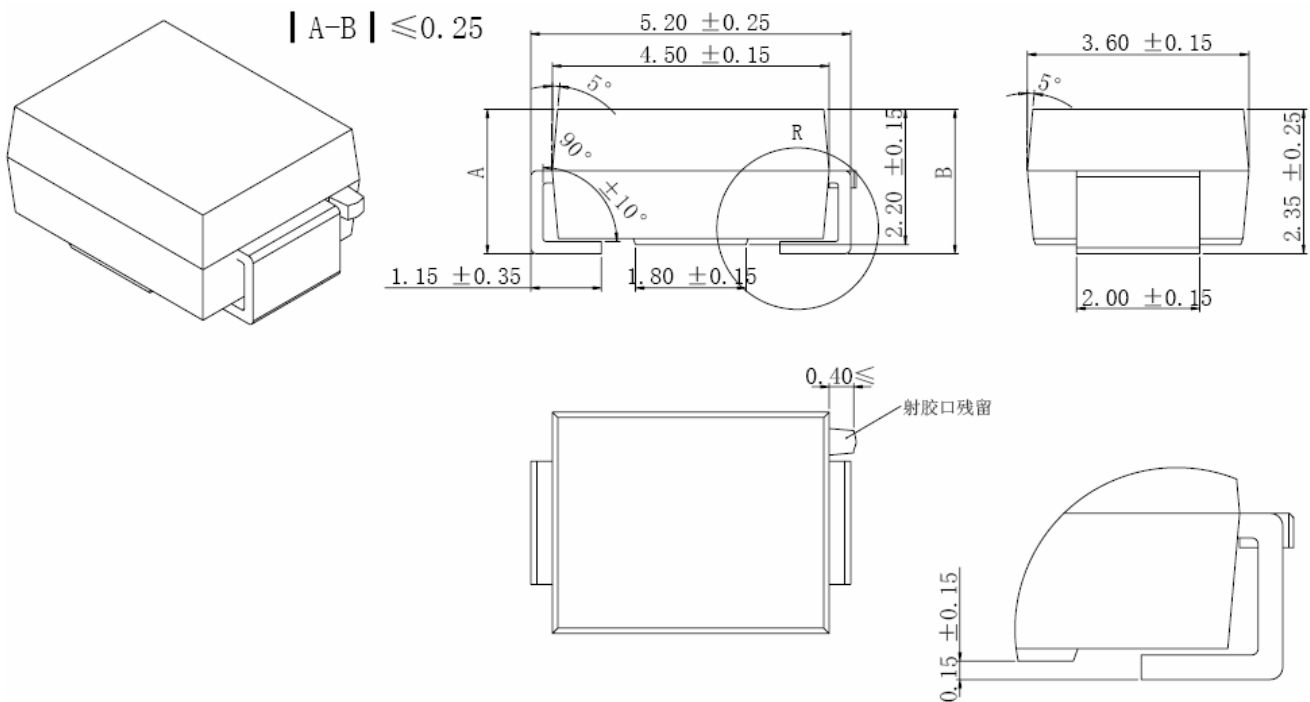
Applications:

- Switching Power Supply
- Power Switching Circuits
- General Purpose

Features:

- Glass Passivated Die Construction
- Ideally Suited for Automatic Assembly
- Low Forward Voltage Drop, High Efficiency
- Low Power Loss
- Super Fast Recovery Time
- Plastic Case Material has UL Flammability Classification Rating 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

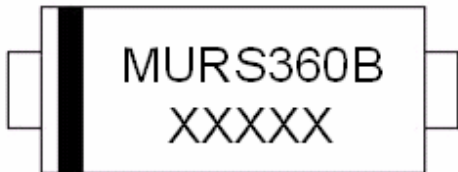
Mechanical Dimensions: In mm



SMB

Marking Diagram:

Where XXXXX is YYWWL



MURS = Device Type
 3 = Forward Current (3A)
 60 = Reverse Voltage (600V)
 B = Package type
 YY = Year
 WW = Week
 L = Lot Number

Cautions: Molding resin
 Epoxy resin UL:94V-0

Ordering Information:

Device	Package	Shipping
MURS360B	SMB (Pb-Free)	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.



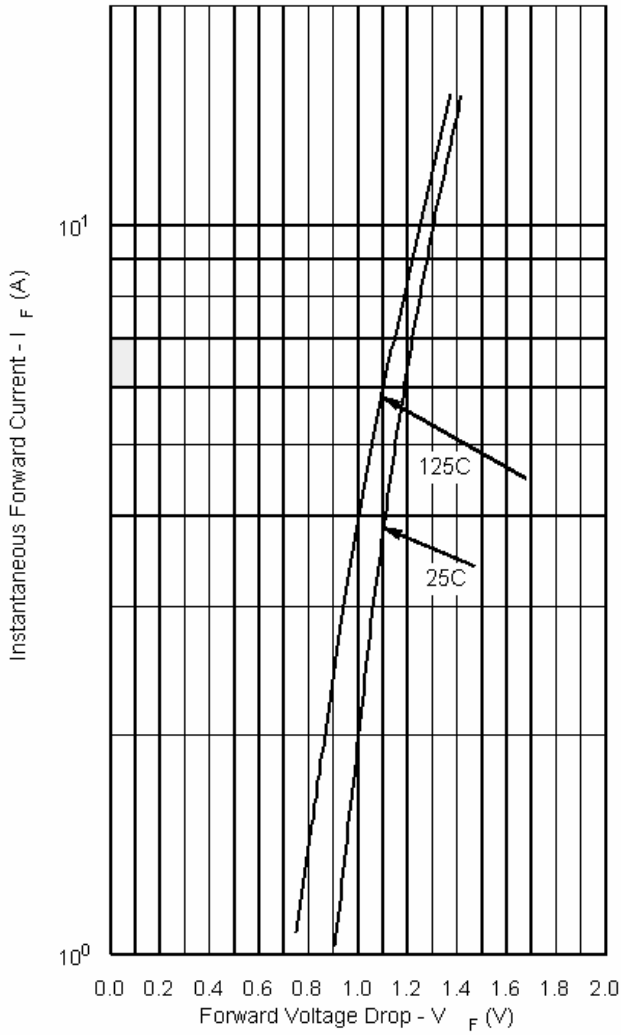
Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

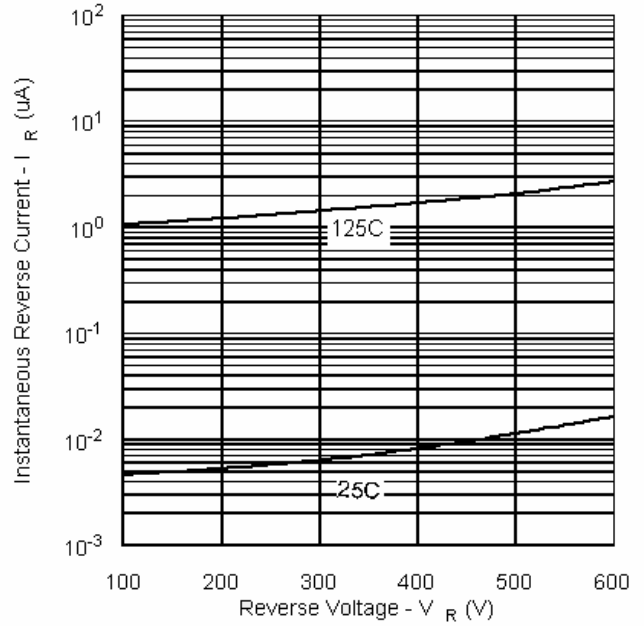
Characteristic	Symbol	MURS360B	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	600	V
RMS Reverse Voltage	V _{R(RMS)}	420	V
Average Rectified Output Current (Note 1) @T _A = 55°C	I _o	3.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	150	A
Forward Voltage (per element) @I _F = 3.0A	V _{FM}	1.25	V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 125°C	I _{RM}	10 500	μA
Maximum Reverse Recovery Time (Note 1)	T _{rr}	50	ns
Typical Thermal Resistance Junction to Ambient (Note 2)	R _{θJA}	25	K/W
Max. Junction Temperature	T _J	-55 to +150	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C
Approximate Weight	wt	0.68	g
Case Style	SMB		

Note: 1. Reverse Recovery Test Conditions: I_F=0.5A, I_R=1.0A, I_{RR}=0.25A
2. Mount on Cu-Pad Size 16mm×16mm on P.C.B.

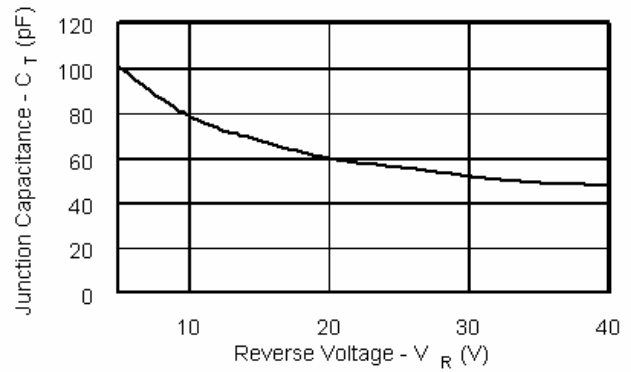
Typical Forward Characteristics



Typical Reverse Characteristics



Typical Junction Capacitance



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